



Material Content Data Sheet



Sales Product Name		BSC028N06NS		Issued		22. July 2019		
MA#		MA003218888						
Package		PG-TDSON-8-50		Weight*		106.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.837	0.79	0.79	7853	7853
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		512	
	non noble metal	iron	7439-89-6	1.090	1.02		10232	
wire	non noble metal	copper	7440-50-8	44.271	41.54	42.62	415466	426338
	noble metal	gold	7440-57-5	0.042	0.04	0.04	395	395
	encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		797
	plastics	epoxy resin	-	3.904	3.66		36640	
	inorganic material	silicondioxide	60676-86-0	38.449	36.08	39.82	360824	398261
leadfinish	non noble metal	tin	7440-31-5	1.264	1.19	1.19	11859	11859
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	272	272
solder	noble metal	silver	7440-22-4	0.030	0.03		281	
	non noble metal	tin	7440-31-5	0.060	0.06		562	
	non noble metal	lead	7439-92-1	1.108	1.04	1.13	10402	11245
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	zinc	7440-66-6	0.018	0.02		173	
	non noble metal	iron	7439-89-6	0.368	0.35		3451	
	non noble metal	copper	7440-50-8	14.930	14.01	14.38	140110	143777
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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